Written by Alice Marshall 18 July 2018

Intel and Micron present an update on the 3D XPoint memory partnership-- the two companies plan to work together on the 2nd generation of the technology, before bringing the collaboration to an end.



The 2nd generation of 3D XPoint technology should be complete sometime on H1 2019, although the companies do not specify whether this involves the sending out of engineering samples, the start of mass productions or the release of commercial products. Either way, once done Intel and Micron will pursue the development of the technology independently, even if both will continue manufacturing products at the Intel-Micron Flash Technologies (IMFT) facility in Lehi, Utah.

But why are Intel and Micron parting ways? According to the announcement, the reason is simply the companies want to optimise the technology for their respective product and business needs. Micron is currently reticent regarding its 3D Xpoint ambitions, while Chipzilla states it plans to continue building on the Optane product range.

"Intel Optane's direct connection to the world's most advanced computing platforms is achieving breakthrough results in IT and consumer applications," the company says. "We intend to build on this momentum and extend our leadership with Optane, which combined with our high-density 3D NAND technology offers the best solutions for today's computing and storage needs."

Go Micron and Intel Announce Update to 3D Xpoint Joint Development Program